



© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 480 I/O TAPE BGA, 37.5 X 37.5 PKG, 1.27 MM PITCH	DOCUMENT NO: 98ASS23799W	REV: J
	STANDARD: JEDEC MO-192, VARIATION BAT-1	
	SOT1752-1	27 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 480 I/O TAPE BGA, 37.5 X 37.5 PKG, 1.27 MM PITCH	DOCUMENT NO: 98ASS23799W REV: J	
	STANDARD: JEDEC M0-192, VARIATION BAT-1	
	SOT1752-1 27 JAN 2016	